Exam.Code:0932 Sub. Code: 33705

Max. Marks: 50

## 2015

## B.E. (Electronics and Communication Engineering)

## Eighth Semester

EC-814: MEMS and Microsystems

Time allowed: 3 Hours

NOTE: Attempt five questions in all, including Question No. I which is compulsory and selecting two questions from each Unit. x-x-xI. (a) How micro actuator works? (b) What is scaling? (c) Why short channel effects occur in small device? (d) Give role of CAD in MEMS. (e) Describe LGA process. [5x2] **UNIT-I** [5] II. (a) What is voltage scaling? Its pros and cons. [5] (b) What is DIBL? How its can be mitigated. III. (a) Explain scaling in electromagnetic forces. [5] (b) Why Silicon Material highly preferred in MEMS devices? [5] (a) Discuss the properties of piezoelectric materials. [5] IV. (b) What is packaging? How packaging materials affect the performance of microsystem. [5] **UNIT-II** V. (a) How diffusion and ion-implantation process works? [5] (b) Describe metallization? Discuss metallization methods. [5] VI. (a) What is etching? Explain dry etching technique. [5] (b) Why sputtering required? Describe sputtering techniques. [5] Write a note on: VII. (a) Bulk micromachining. [5] [5] (b) Microsystem packaging.